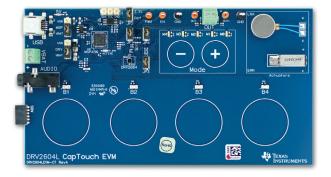
# DRV2604LEVM-CT Quick-Start Guide

# Start Here

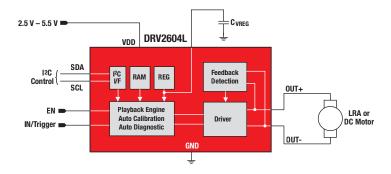






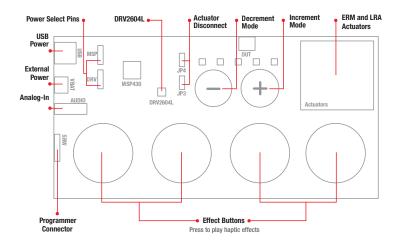
# **Evaluation Kit Contents**

- DRV2604L LRA / ERM haptics driver with automatic overdrive and braking for ERM and LRAs
- Eccentric rotating mass motor (ERM)
- Linear resonant actuator (LRA)
- Programmable MSP430<sup>™</sup> with haptic effects
- Capacitive touch buttons
- Mini-USB cable



# **Getting Started**

- 1. Verify jumpers MSP and DRV, next to the USB connector, are connected to the USB pin.
- 2. Plug the board into an available USB power source (computer or wall charger) using the included USB cable.
- 3. Board will enter a power up sequence and the 5 V indicator will light up.
- 4. Use the large buttons to play effects and the "+" and "-" buttons to switch between modes. Each mode has a different set of effects.



# **Mode and Effects**

Mode	Button	Description	Actuator	Waveform Location	Interface	
	B1	Click + Bounce	ERM		Internal Trigger	
Mode Off LEDs Off	B2	Ramp Up + Click	LRA	RAM		
	B3	Gallop Alert	ERM		(I <sup>2</sup> C)	
	B4	Pulsing Alert	LRA			
	B1	StrongClick	FRM	RAM	Ext. Level Trig.	
Mode 4 LED M4 On	B2	Bump + Release			Internal Trigger	
	B3	Double Strong Click	ENIVI		Ext. Edge Trig.	
	B4 Click (Open Lo	Click (Open Loop)		µController	PWM	
	B1	StrongClick				Ext. Level Trig.
Mode 3 LED M3 On	B2	Single-Cycle Click	LRA		Internal Trigger	
	B3	Single-Cycle Click with braking			Ext. Edge Trig.	
	B4	Click (Open Loop)		µController	PWM	
	B1	Buzz Auto-Resonance ON	LRA		RTP (I <sup>2</sup> C)	
Mode 2 LED M2 On	B2	Buzz Auto-Resonance OFF	LRA	uControllor	PWM	
	B3	Buzz Alert	ERM	μοσητιοιιεί	PWM	
	B4	Scroll Wheel	LRA		RTP (I2C)	
	B1	Click with braking			Internal Trigger (I²C)	
Mode 1	B2	Click without braking	ERM &	RAM		
LED M1 On	B3	Click with braking (open loop)	LRA			
	B4	Selects ERM or LRA				
Mode 0 LED MO On	B1	Auto-Calibration	ERM	Internal	Internal Trigger (I²C)	
	B2	Auto-Calibration	LRA	Routine		
	B3	Click	FRM/I BA	RAM	Internal Trigger (I²C)	
	B4	Buzz	Enivi/LKA			

## **Features and Benefits**



Embedded RAM Integrated RAM can store over 100 customized waveforms that can be triggerred via I<sup>2</sup>C or a GPIO



#### Immersion-Compatible

Works seamlessly with Immersion TouchSense® 3000

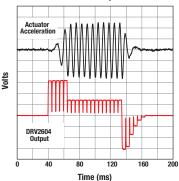
#### **Smart Loop Architecture**



#### Auto-Resonance Detection

Automatically track the resonant frequency of an LRA; maximize vibration strength and improve consistency across devices

#### ERM Closed Loop Buzz





# Automatic Diagnostics

Automatically detect the status of the actuator



## Automatic Calibration

Automatically detect and configure the closed-loop feedback coefficients for every actuator



#### **Closed Loop Feedback**

Improve the response time of ERM and LRA actuators with automatic overdrive and braking

# **Design Resources and References**



#### E2E Haptic Forum ti.com/hapticforum

Available on ti.com/drv2604L

- DRV2604L datasheet
- Complete DRV2604LEVM-CT User's Guide
- · Schematics and layout
- EVM source code and binaries

Get more information on TI's solutions for touch feedback-enabled applications at ti.com/haptics

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